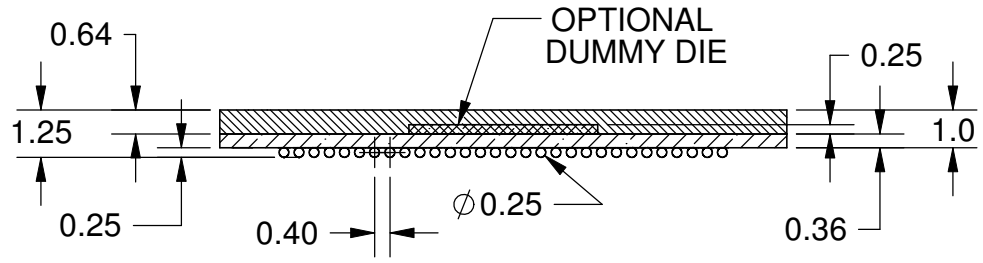
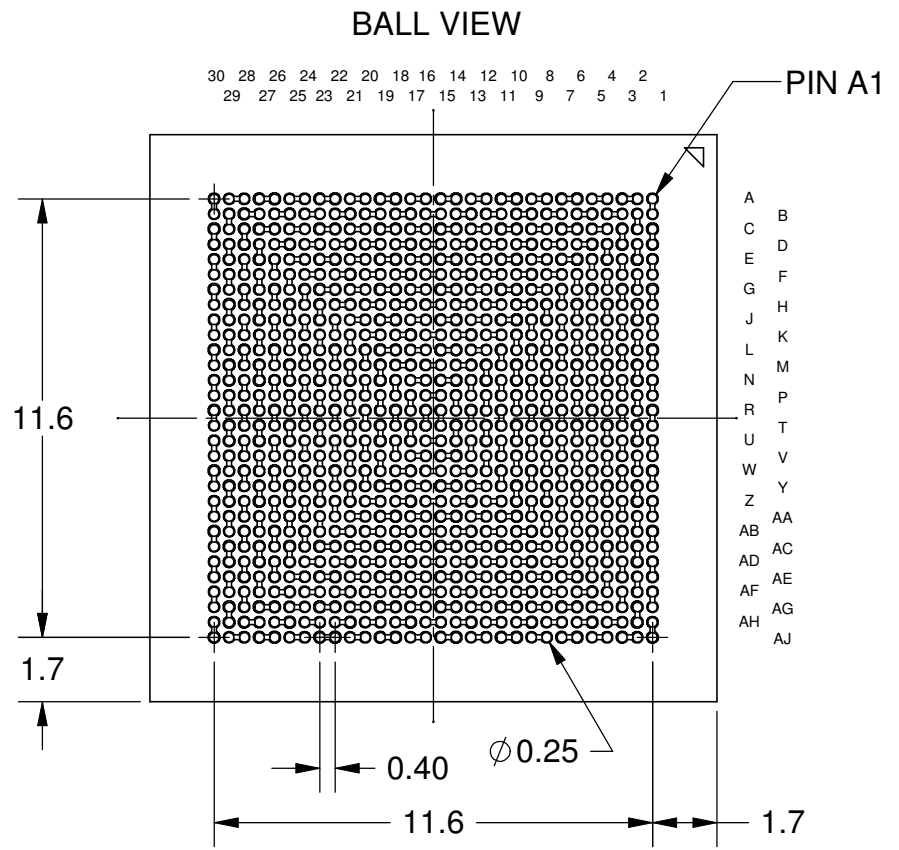
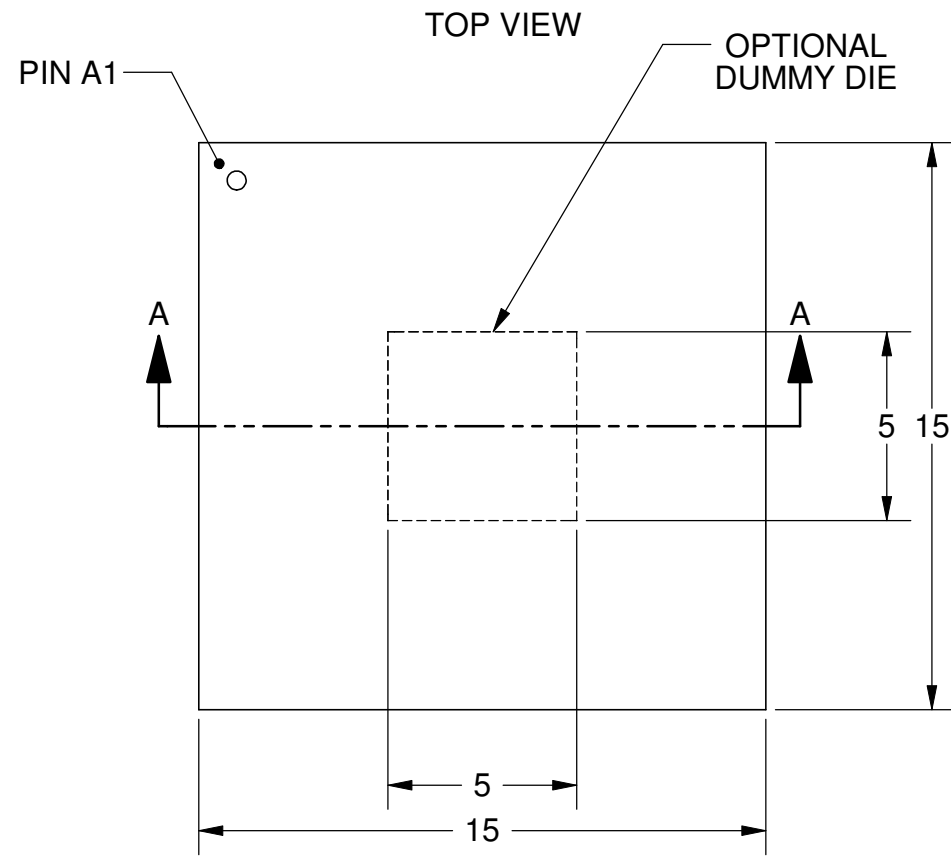


REVISIONS				
DATE	REV.	ECO	DESCRIPTION	APPROVED



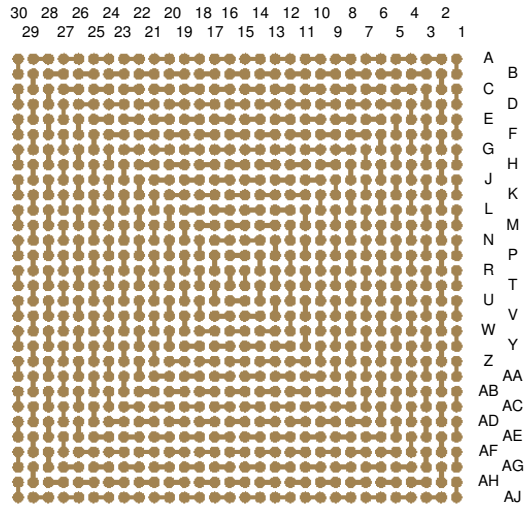
SECTION A-A

- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
  - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
  - 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
  - 4) SOLDER MASK DEFINED PAD OPENING: 0.22mm [8.7 MIL].
  - 5) PAD Cu DIAMETER: 0.305mm [12 MIL].
  - 6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
  - 7) DUMMY DIE IS OPTIONAL.
  - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
  - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

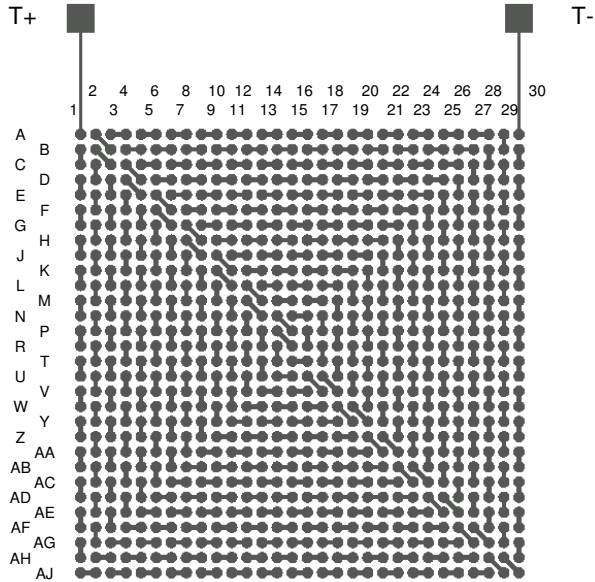
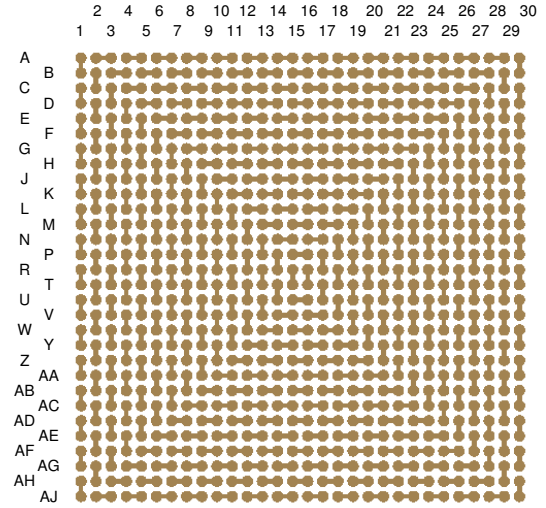
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA900T.4C-DC309	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
BGA900T.4C-DC309D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA900T.4-DC309	Sn63/Pb37	NO	NO	NO
BGA900T.4-DC309D	Sn63/Pb37	NO	NO	YES

TOLERANCE UNLESS NOTED	APPROVALS	DATE			
X.XX +/- 0.01	DRAWN J. Hines	9/16/2010			
X.XXX +/- 0.005			ENG	BGA900T.4-DC309	
X.XXXX +/- 0.0005	MFG	DAISY CHAIN DUMMY			
ANGLES +/- 0.5°	QA	SCALE	SIZE	DRAWING NO.	REV
ALL DIMENSIONS IN	CUST	5:1	A	543091	A
<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS	REVISED	DO NOT SCALE DRAWING			SHEET 1 OF 2
THIRD ANGLE PROJECTION					

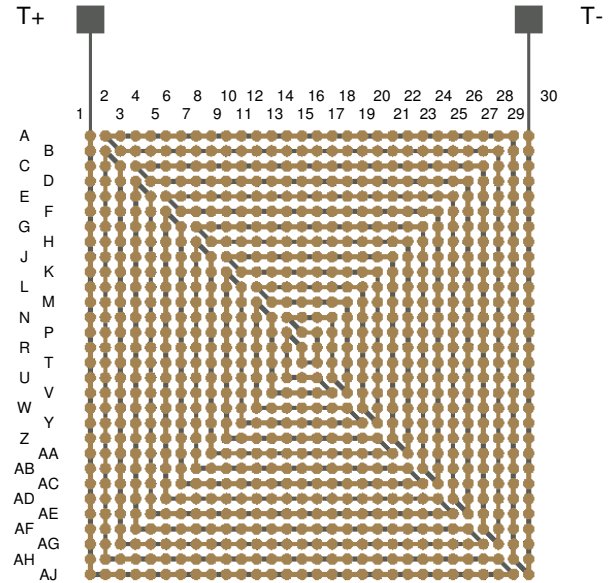
### BALL VIEW



### BOTTOM SIDE (TOP X-RAY VIEW)



### TEST VEHICLE BOARD



### AFTER MOUNTING

**Notes:**

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.305mm [12 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm [5 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.22mm [8.7 MIL].

<b>TopLine</b> ®			
TITLE <b>BGA900T.4-DC309</b> <b>DAISY CHAIN DUMMY</b>			
SCALE	SIZE	DRAWING NO.	REV
5:1	A	543091	A
DO NOT SCALE DRAWING			SHEET 2 OF 2